Schottky Barrier Diode

Schottky barrier diodes are optimized for very low forward voltage drop and low leakage current and are used in a wide range of dc-dc converter, clamping and protection applications in portable devices. NSR0520V2 in a SOD-523 miniature package enables designers to meet the challenging task of achieving higher efficiency and meeting reduced space requirements.

Features

- Very Low Forward Voltage Drop 325 mV @ 100 mA
- Low Reverse Current 8.0 μA @ 10 V
- Continuous Forward Current 500 mA
- Power Dissipation with Minimum Trace 170 mW
- Very High Switching Speed 12 ns @ 10 mA
- Low Capacitance 35 pF @ 1.0 V
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping and Protection

Markets

- Mobile Handsets
- MP3 Players
- Digital Camera and Camcorders
- Notebook PCs & PDAs
- GPS

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	V _R	20	Vdc
Forward Continuous Current (DC)	lF	500	mA
Non-Repetitive Peak Forward Surge Current	I _{FSM}	2.0	Α
Repetitive Peak Forward Current (Pulse Wave = 1 sec, Duty Cycle = 66%)	I _{FRM}	1.5	Α
ESD Rating: Human Body Model Machine Model	ESD	Class 3B Class C	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



ON Semiconductor®

http://onsemi.com

20 VOLT SCHOTTKY BARRIER DIODE





SOD-523 CASE 502

MARKING DIAGRAM



AA = Device Code M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation position may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
NSR0520V2T1G	SOD-523 (Pb-Free)	3000/Tape & Reel
NSVR0520V2T1G	SOD-523 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

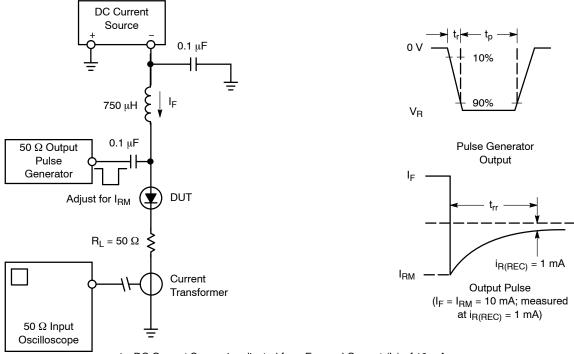
THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ T _A = 25°C	R _{θJA}	600	°C/W
	P _D	170	mW
Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ T _A = 25°C	R _{θJA}	300	°C/W
	P _D	340	mW
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +125	°C

- 1. Mounted onto a 4 in square FR-4 board 10 mm sq. 1 oz. Cu 0.06" thick single-sided. Operating to steady state.
- 2. Mounted onto a 4 in square FR-4 board 1 in sq. 1 oz. Cu 0.06" thick single-sided. Operating to steady state.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Leakage (V _R = 10 V) (V _R = 20 V)	I _R		8.0 75	30	μΑ
Forward Voltage (I _F = 10 mA) (I _F = 100 mA) (I _F = 500 mA)	V _F		255 325 410	320 390 480	mV
Total Capacitance (V _R = 1.0 V, f = 1 MHz)	СТ		35		pF
Reverse Recovery Time $(I_F = I_R = 10 \text{ mA}, I_R = 1.0 \text{ mA})$	t _{rr}		12.0		ns



- 1. DC Current Source is adjusted for a Forward Current (I_F) of 10 mA.
- 2. Pulse Generator Output is adjusted for a Peak Reverse Recovery Current I_{RM} of 10 mA.
- 3. Pulse Generator transition time << t_{rr}.

 4. $I_{R(REC)}$ is measured at 1 mA. Typically 0.1 X I_{RM} or 0.25 X I_{RM} .
- 5. t_p » t_{rr}

Figure 1. Recovery Time Equivalent Test Circuit

TYPICAL CHARACTERISTICS

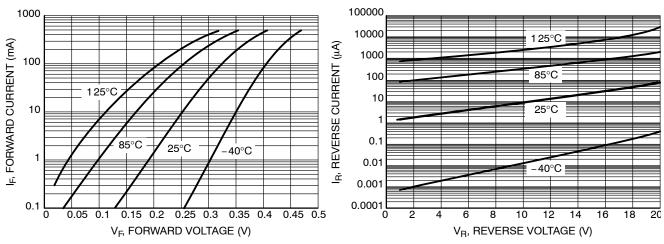


Figure 2. Figure 3.

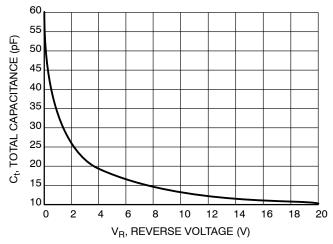
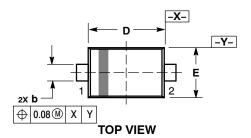
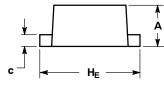


Figure 4.

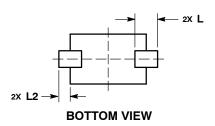
PACKAGE DIMENSIONS

SOD-523 **CASE 502 ISSUE E**









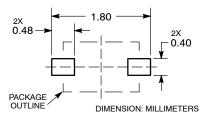
NOTES

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
 MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.50	0.60	0.70	
b	0.25	0.30	0.35	
С	0.07	0.14	0.20	
D	1.10	1.20	1.30	
E	0.70	0.80	0.90	
HE	1.50	1.60	1.70	
L	0.30 REF			
L2	0.15	0.20	0.25	

RECOMMENDED **SOLDERING FOOTPRINT***



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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